

FFATURFS:

- · Bus switches provide zero delay paths
- · Low switch on-resistance
- · TTL-compatible input and output levels
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- · Hot insertion capability
- · Very low power dissipation
- · Available in TSSOP package

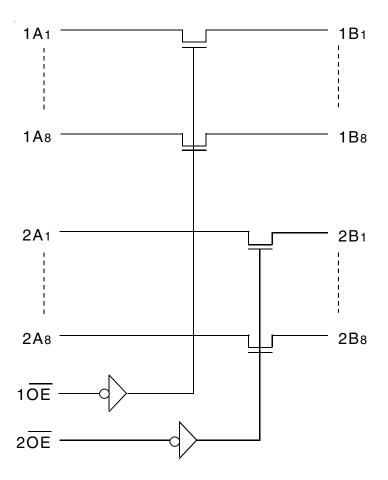
DESCRIPTION:

The FST163245 belongs to IDT's family of Bus switches. Bus switch devices perform the function of connecting or isolating two ports without providing any inherent current sink or source capability. Thus they generate little or no noise of their own while providing a low resistance path for an external driver. These devices connect input and output ports through an n-channel FET. When the gate-to-source junction of this FET is adequately forward-biased the device conducts and the resistance between input and output ports is small. Without adequate bias on the gate-to-source junction of the FET, the FET is turned off, therefore with no Vcc applied, the device has hot insertion capability.

The low on-resistance and simplicity of the connection between input and output ports reduces the delay in this path to close to zero.

The FST163245 is pin compatible with and functionally similar to FCT16245.

FUNCTIONAL BLOCK DIAGRAM

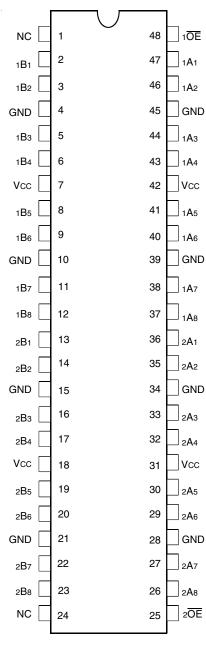


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INDUSTRIAL TEMPERATURE RANGE

JUNE 2006

PIN CONFIGURATION



TSSOP TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7	V
Tstg	Storage Temperature	-65 to +150	°C
Іоит	Maximum Continuous Channel Current	128	mA

NOTES:

- 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. Vcc, Control, and Switch terminals.

CAPACITANCE⁽¹⁾

Symbol Parameter		Conditions ⁽²⁾	Тур.	Unit
CIN	Control Input Capacitance		6	pF
CI/O	Switch Input/Output Capacitance	Switch Off	12	pF

NOTES

- 1. Capacitance is characterized but not tested.
- 2. TA = 25°C, f = 1MHz, VIN = 0V, VOUT = 0V.

PIN DESCRIPTION

Pin Names	I/O	Description	
1A1-8, 2A1-8	I/O	Bus A	
1B1-8, 2B1-8	I/O	Bus B	
10E, 20E	I	Bus Switch Enable (Active LOW)	

FUNCTION TABLE(1)

Inputs	
хŌĒ	Outputs
L	Connect A to B
Н	Disconnect A from B

NOTE:

- 1. H = HIGH Voltage Level
 - L = LOW Voltage Level

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, VCC = 5.0V ± 10 %

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Тур. ⁽²⁾	Max.	Unit
VIH	Control Input HIGH Voltage	Guaranteed Logic HIGH for Contr	Guaranteed Logic HIGH for Control Inputs		_	1	V
VIL	Control Input LOW Voltage	Guaranteed Logic LOW for Control Inputs		_	_	0.8	V
lін	Control Input HIGH Current	Vcc = Max.	VI = VCC	_	_	±1	μΑ
lıL	Control Input LOW Current		VI = GND	_	_	±1	
Іоzн	Current During	Vcc = Max., Vo = 0 to 5V		_	_	±1	μΑ
lozl	Bus Switch Disconnect			_	_	±1	
Vik	Clamp Diode Voltage	VCC = Min., IIN = -18mA		_	-0.7	-1.2	V
loff	Switch Power Off Leakage	$VCC = 0V$, $VIN \text{ or } VO \le 5.5V$		_	_	±1	μΑ
Icc	Quiescent Power Supply Current	Vcc = Max., Vin = GND or Vcc		_	0.1	3	μA

BUS SWITCH IMPEDANCE OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, VCC = $5.0V \pm 10\%$

Symbol	Parameter	Test Conditions	Min.	Typ. ⁽¹⁾	Max.	Unit
Ron	Switch On Resistance ⁽²⁾	Vcc = Min., Vin = 0V, Ion = 30mA	1	5	7	Ω
		Vcc = Min., Vin = 2.4V, Ion = 15mA	_	10	15	
los	Short Circuit Current ⁽³⁾	A(B) = 0V, $B(A) = VCC$	100	_		mA

NOTES:

- 1. Typical values are at Vcc = 5.0V, +25°C ambient.
- 2. The voltage drop between the indicated ports divided by the current through the switch.
- 3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
Δlcc	Quiescent Power Supply Current TTL Inputs HIGH	$Vcc = Max.$ $Vin = 3.4V^{(3)}$		ı	0.5	1.5	mA
ICCD	Dynamic Power Supply Current ^(4,5)	Vcc = Max., Outputs Open One Enable Pin Toggling 50% Duty Cycle	VIN = VCC VIN = GND		240	320	μΑ/ MHz/ Enable
Ic	Total Power Supply Current ⁽⁶⁾	Vcc = Max., Outputs Open Two Enable Pins Toggling	VIN = VCC VIN = GND	_	4.8	6.4	mA
		fi = 10MHz 50% Duty Cycle	VIN = VCC VIN = 3.4V	_	5.3	7.9	

NOTES:

- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type. TA = -40°C to +85°C
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V). All other inputs at Vcc or GND. Switch inputs do not contribute to ΔIcc .
- 4. This parameter represents the current required to switch the internal capacitance of the control inputs at the specified frequency.

 Switch inputs generate no significant power supply currents as they transition. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. CPD = ICCD/VCC
 - CPD = Power Dissipation Capacitance
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
 - $IC = ICC + \Delta ICC DHNT + ICCD (fiN)$
 - Icc = Quiescent Current
 - Δ Icc = Power Supply Current for a TTL High Input (VIN = 3.4V)
 - DH = Duty Cycle for TTL Inputs High
 - NT = Number of TTL Inputs at DH
 - ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
 - fi = Control Input Frequency
 - N = Number of Control Inputs Toggling at fi

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

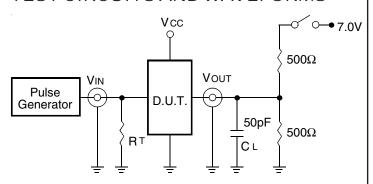
Industrial: TA = -40°C to +85°C, Vcc = 5.0V ± 10 %

Symbol	Description	Min. ⁽¹⁾	Тур.	Max.	Unit
t PLH	Data Propagation Delay	_	_	0.25	ns
t PHL	A to B, B to A ⁽²⁾				
t PZH	Switch CONNECT Delay	1.5	_	6.5	ns
t PZL	xOE to A or B				
t PHZ	Switch DISCONNECT Delay	1.5	_	5.5	ns
t PLZ	xOE to A or B				
Qcı	Charge Injection During Switch DISCONNECT	_	1.5	_	рC
	x OE to A or B ⁽³⁾				

NOTES:

- 1. See test circuits and waveforms.
- 2. The bus switch contributes no Propagation Delay other than the RC Delay of the load interacting with the RC of the switch.
- 3. |Qci| is the charge injection for a single switch DISCONNECT and applies to either single switches or multiplexers. Charge injection is reduced because the injection from the DISCONNECT of the first path is compensated by the CONNECT of the second path.

TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs

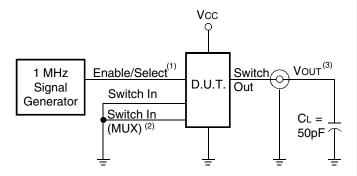
SWITCH POSITION

Test	Switch
Open Drain	
Disable Low	Closed
Enable Low	
All Other Tests	Open

DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

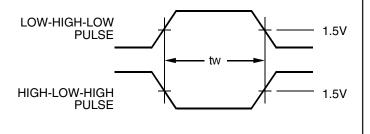
RT = Termination resistance: should be equal to Zout of the Pulse Generator.



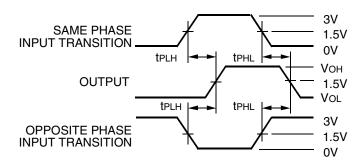
Charge Injection

NOTES:

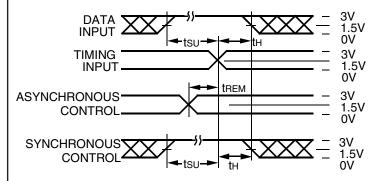
- Select is used with multiplexers for measuring IQDcII during multiplexer select. During all other tests Enable is used.
- 2. Used with multiplexers to measure IQpcil only.
- Charge Injection = ΔVouT CL, with Enable toggling for IQcII or Select toggling for IQpcII. ΔVouT is the change in VouT and is measured with a 10MΩ probe.



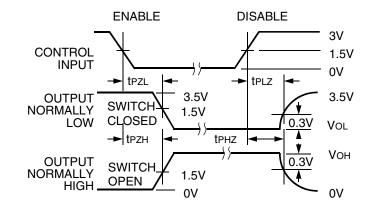
Pulse Width



Propagation Delay



Set-up, Hold, and Release Times

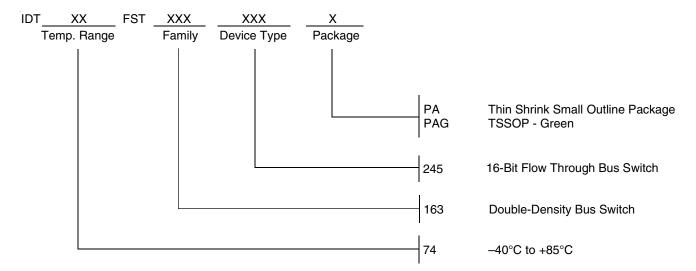


Enable and Disable Times

NOTES

- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; tF \leq 2.5ns; tR \leq 2.5ns.

ORDERING INFORMATION





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